LIQUID CRYSTAL DISPLAY MODULE

Product Specification

DENSITRON	**STANDARD LCD MODULE**	
PRODUCT NUMBER	**LWM12232E-SERIES**	
DEFINITION	**122*32 dots**	**Date 08/08/08**

INTERNAL APPROVALS				
Quality Mgr	Product Mgr	Project Leader	Mech. Eng	Electr. Eng
Pat CHANG	Stéphan KIEFFER	Adrian SMYTH	Pat CHANG	Eric HUNG
Date: 19/02/07	Date: 19/02/07	Date: 09/02/07	Date: 17/02/07	Date: 17/02/07

TABLE OF CONTENTS

REVISION RECORD

Rev.	Date	Page	Chapt.	Comment	ECR no.
1	29/02/2007			Initial Specification	

1 PART NUMBERING SYSTEM

LWM 12232E - BW - WCF *

Densitron mono module ① ② ③ ④ ⑤ ⑥

① Characters x Row format

② Model serials number

③ Display mode and backlight type :

A = Reflective (without backlight) =

B* = Transflective positive LEDS array type backlight (BG, BA, BW, BR...)

B*(E) = Transflective LEDS edge type backlight (BGE, BAE, BWE, BR…)

B = Transflective CFL

C* = Transflective positive EL backlight (CB, CW)

D* = Transmissive negative EL backlight (DB, DW)

E = CFL

E* = Transmissive negative LEDS array type backlight (EG, EA, EW, ER…)

E*(E) = Transmissive negative LEDS edge type backlight (EGE, EAE, EWE, ERE…)

(color LED or EL backlight = G/ yellow-green, A/ amber, W/ white, R/ red, B/blue, …)*

④ Temperature range and power supply

D = Standard temperature range; negative supply voltage required (0°C~+50°C)

S = Standard temperature range; on board negative voltage generator (0°C~+50°C)

H= Wide temperature range; negative supply voltage required (-20°C ~+70°C)

W= Wide temperature range; on board negative voltage generator (-20°C ~+70°C)

⑤ Fluid type and compensation circuit option

NY = STN yellow-green glass, without temperature compensation circuit

CY = STN yellow green glass, with temperature compensation circuit on board

NG = STN gray glass without temperature compensation circuit

CG = STN gray glass with temperature compensation circuit

NB = STN blue glass, without temperature compensation circuit

CB = STN blue glass with temperature compensation circuit

NF = FSTN black and white glass without temperature compensation circuit

CF = FSTN black and white glass with temperature circuit on board

⑥ Special code for customized features

Please refer to our commercial office

Remarks and definitions :

1°) Display mode and backlight type :

- Reflective polarizer, no backlight, usable only in good ambient light conditions.
- Transflective polarizer uses a background backlight and a mirror reflector, usable in all lighting conditions.
- Transmissive polarizer needs the backlight switched on continuously, usable mostly in low ambient light conditions
- EL (electro-luminescent), uniform brightness, short life time (8000 hours max), needs EL inverter, low current consumption, low thickness.
- LED (light emitting diode), uniform brightness, long lifetime (100 000 hours), doesn't need inverter, reliable in vibration and shock environment, different colors available.

Array version is a direct lighting type, available in standard form, uniform and good brightness on all the active area.

Edge version is an edge lighting type providing a low consumption backlight, has a low thickness and brightness.

- Positive mode has dark pixels on a light background
- Negative mode has light pixels in a dark background and is normally used only with a transmissive polarizer as it needs a backlight on to be visible.

2°) Fluid type :

- STN yellow green or gray LCD has a yellow green or gray background with dark blue pixels and offers a good contrast.
- FSTN LCD is to produce very high contrast with black and white pixels using a film polarizer

2 MAIN FEATURES

ITEM	CONTENTS
Display Format	122 x 32 dot
Overall Dimensions	80.0 x 36.0 x 10.2MAX)
Viewing Area	60.0 x 18.0
LCD type	STN, FSTN
Mode	Available in Reflective/Positive /Negative modes
Viewing Angle	6 and 12 O' clock
Duty	1/32
Driver IC	SED 1520 or equivalent
Backlight type	None /EL/ LED
Backlight colour	Yellow Green / White / Amber/Red/Blue/Tri-Colour
DC/DC converter	None/Included
Operating temperature	From 0/+50°C to -20°/+70°C
Storage temperature	From -20°/+70°C to -30°/+80°C

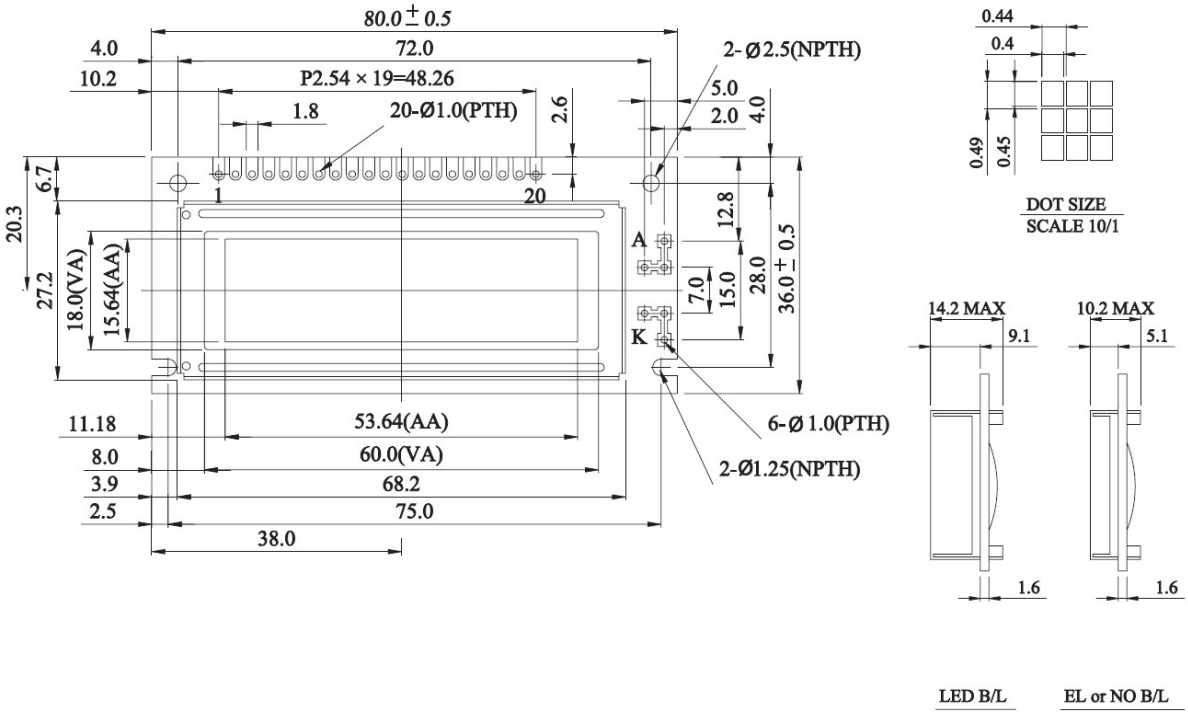
3 MECHANICAL SPECIFICATION

3.1 MECHANICAL CHARACTERISTICS

Item	Dimension	Unit
Number of Characters	122 x 32 dot	
Module dimension	80.0 x 36.0 x 14.2(MAX)-LED	mm
	80.0 x 36.0 x 10.2(MAX)-No BL/EL	
View area	60.0 x 18.0	mm
Active area	53.64 x 15.64	mm
Dot size	0.4 x 0.45	mm
Dot pitch	0.44 x 0.49	mm

3.2 MECHANICAL DRAWING

Version LED, EL



4 ELECTRICAL SPECIFICATION

4.1 ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	0	—	+50	℃
Storage Temperature	T_{ST}	-10	—	+60	℃
Input Voltage	V_I	0	—	V_{DD}	V
Supply Voltage For Logic	V_{DD}	0	—	6.7	V
Supply Voltage For LCD	V_{DD}-V_{LCD}	0	—	-10	V

Note 1: Background colour changes slightly depending on ambient temperature. This phenomenon is reversible. Ta≤70 °C: 75% RH max

Note 2: Ta≤80 °C: 75% RH max

4.2 ELECTRICAL CHARACTERISTICS

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	V_{DD}-V_{SS}	—	4.75	5.0	5.25	V
Supply Voltage For LCD	V_{DD}-V_0	Ta=0℃	—	—	5.1	V
		Ta=25℃	—	4.8	—	V
		Ta=+50℃	4.5	—	—	V
Input High Volt.	V_{IH}	—	0.7V_{DD}	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	0	—	0.3V_{DD}	V
Output High Volt.	V_{OH}	—	2.4	—	—	V
Output Low Volt.	V_{OL}	—	—	—	0.4	V
Supply Current	I_{DD}	—	—	1.2	—	mA

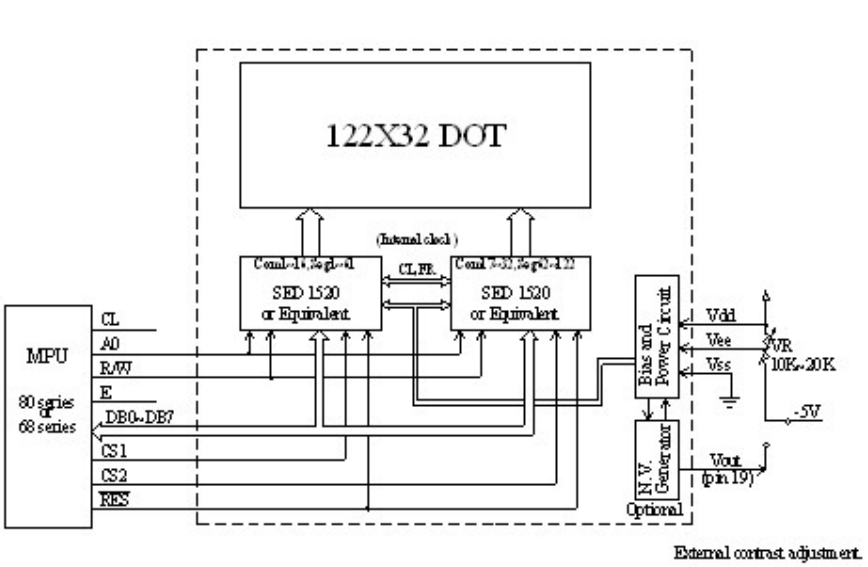
VSS = 0 V, Ta = 25 °C

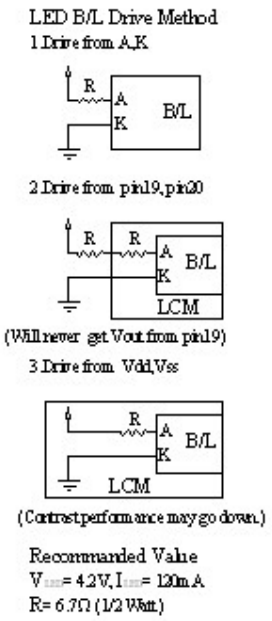
* I_{DD} measurement condition is for all pattern ON

4.3 INTERFACE PIN ASSIGNMENT

Pin No.	Symbol	Level	Description
1	V_{ss}	0V	Ground
2	V_{dd}	5V	Power supply for logic
3	Vo	(Variable)	Operating voltage for LCD
4	A0	H/L	H : Data L : Instruction
5	CS1	H/L	Chip select signal for IC1
6	CS2	H/L	Chip select signal for IC2
7	CL	—	External clock 2KHz
8	E(/RD)	H/L	Enable Signal (/RD is for 80 series MPU read signal)
9	R/~~W~~ (/WR)	H/L	H : Read ; L : Write (/WR is for 80 series MPU write signal)
10	DB0	H/L	Data bus
11	DB1	H/L	Data bus
12	DB2	H/L	Data bus
13	DB3	H/L	Data bus
14	DB4	H/L	Data bus
15	DB5	H/L	Data bus
16	DB6	H/L	Data bus
17	DB7	H/L	Data bus
18	RES	H/L	68-series MPU when H→L the LCM is reset. 80- series MPU when L→H the LCM is reset. High level:68-series MPU interface Low level:80-series MPU interface
19	A	+4.2V	LED +
20	K	GND	LED -

4.4 Interface Block Diagram

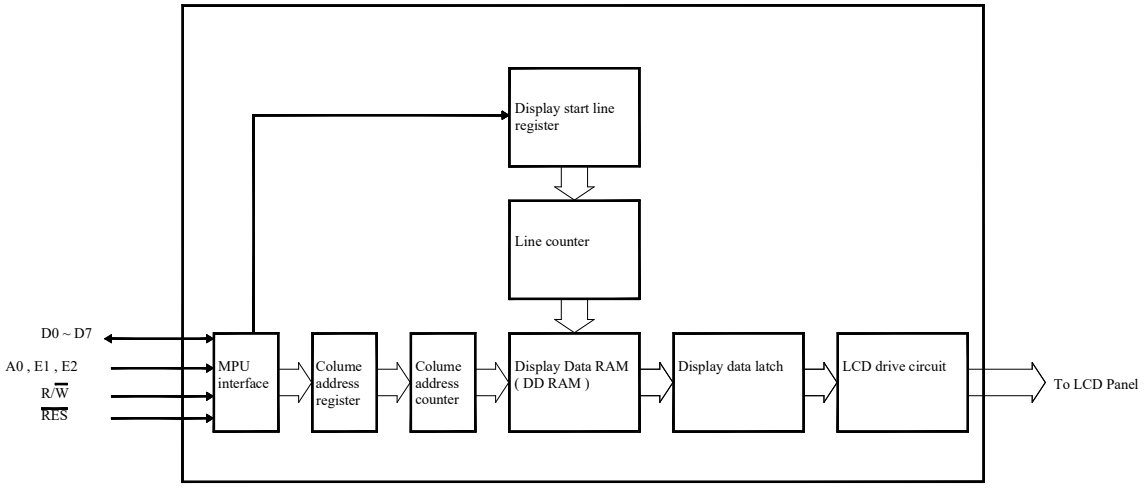




4.5 DISPLAY CONTROL INSTRUCTION

◆Block Diagram

This 122×32 dots LCD Module built in two SBN1661G_M18-D LSI controller.



◆MPU interface

The SBN1661G_M18-D controller transfers data via 8-bit bi-directional data buses (Do to D7), it can fit any MPU if it corresponds to SBN1661G_M18-D Read and Write Timing Characteristics.

◆Data transfer

The SBN1661G_M18-D driver uses the A0, E and R/W signals to transfer data between the system MPU and internal registers, The combinations used are given in the table below.

A0	R/W	Function
1	1	Read display data
1	0	Write display data
0	1	Read status
0	0	Write to internal register (command)

◆Busy flag

When the Busy flag is logical 1, the SBN1661G_M18-D series is executing its internal operations. Any command other than Status Read is rejected during this time. The Busy flag is output at pin D7 by the Status Read command. If an appropriate cycle time (t_{CYC}) is given, this flag needs not be checked at the beginning of each command and, therefore, the MPU processing capacity can greatly be enhanced.

◆Display Start Line and Line Count Registers

The contents of this register form a pointer to a line of data in display data RAM corresponding to the first line of the display (COM0), and are set by the Display Start Line command.

◆Column Address Counter

The column address counter is a 7-bit pre-settable counter that supplies the column address for MPU access to the display data RAM. See Figure 1. The counter is incremented by one every time the driver receives a Read or Write Display Data command. Addresses above 50H are invalid, and the counter will not increment past this value. The contents of the column address counter are set with the Set Column Address command.

◆Display Data RAM

The display data RAM stores the LCD display data, on a 1-bit per pixel basis. The relation-ship between display data, display address and the display is shown in Figure 1.

◆Page Register

The page register is a 2-bit register that supplies the page address for MPU access to the display data RAM. See Figure 1. The contents of the page register are set by the Set Page Register command.

Page address	DATA	Line address	Common output
D1,D2= 0,0	D0	00H	COM 0
	D1	01H	COM 1
	D2	02H	COM 2
	D3	03H	COM 3
	D4	04H	COM 4
	D5	05H	COM 5
	D6	06H	COM 6
	D7	07H	COM 7
0,1	D0	08H	COM 8
	D1	09H	COM 9
	D2	0AH	COM 10
	D3	0BH	COM 11
	D4	0CH	COM 12
	D5	0DH	COM 13
	D6	0EH	COM 14
	D7	0FH	COM 15
1,0	D0	10H	COM 16
	D1	11H	COM 17
	D2	12H	COM 18
	D3	13H	COM 19
	D4	14H	COM 20
	D5	15H	COM 21
	D6	16H	COM 22
	D7	17H	COM 23
1,1	D0	18H	COM 24
	D1	19H	COM 25
	D2	1AH	COM 26
	D3	1BH	COM 27
	D4	1CH	COM 28
	D5	1DH	COM 29
	D6	1EH	COM 30
	D7	1FH	COM 31

Coloum address																								
ADC	D0=0	00H	01H	02H	03H	04H	05H	06H	———	3AH	3BH	3CH	———	4DH	4EH	4FH								
	D0=1	4FH	4EH	4DH	4CH	4BH	4AH	49H	———				———	02H	01H	00H								
	seg pin	1	2	3	4	5	6	7	———	59	60	61	———	78	79	80								

SED1520

SED1521

Figure 1: page and column address

* The 122*32 dots display area is consist of two 61*32. The interface control pin E1 enables the left 61*32,E2 enables the right 61*32.

The host microcontroller can issue commands to the SBN1661G_X. Table 27 lists all the commands. When issuing a command, the host microcontroller should put the command code on the data bus. The host microcontroller should also give the control bus C/D, E(RD), and R/W(WR) proper value and timing.

Commands

COMMAND	COMMAND CODE								FUNCTION
	D7	D6	D5	D4	D3	D2	D1	D0	
Write Display Data	Data to be written into the Display Data Memory.								Write a byte of data to the Display Data Memory.
Read Display Data	Data read from the Display Data Memory.								Read a byte of data from the Display Data Memory.
Read-Modify-Write	1	1	1	0	0	0	0	0	Start Read-Modify-Write operation.
END	1	1	1	0	1	1	1	0	Stop Read-Modify-Write operation.
Software Reset	1	1	1	0	0	0	1	0	Software Reset.

Write Display Data

The Write Display Data command writes a byte (8 bits) of data to the Display Data Memory. Data is put on the data bus by the host microcontroller. The location which accepts this byte of data is pointed to by the Page Address Register and the Column Address Register. At the end of the command operation, the content of the Column Address Register is automatically incremented by 1.

The setting of the control bus for issuing Write Display Data command

$\overline{C}$/D	E/($\overline{RD}$)	R/$\overline{W}$($\overline{WR}$)
1	1	0

Read Display Data

The Read Display Data command starts a 3-step operation.

1. First, the current data of the internal 8-bit output latch of the Display Data Memory is read by the microcontroller, via the 8-bit data bus DB0~DB7.
2. Then, a byte of data of the Display Data Memory is transferred to the 8-bit output latch from a location specified by the Page Address Register and the Column Address Register,
3. Finally, the content of the Column Address Register is automatically incremented by one. Fig. 16 shows the internal 8-bit ouptut latch located between the 8-bit I/O data bus and the Display Data Memory cell array. Because of this internal 8-bit output latch, a dummy read is needed to obtain correct data from the Display Data Memory. For Display Data Write operation, a dummy write **is not** needed, because data can be directly written from the data bus to internal memory cells.

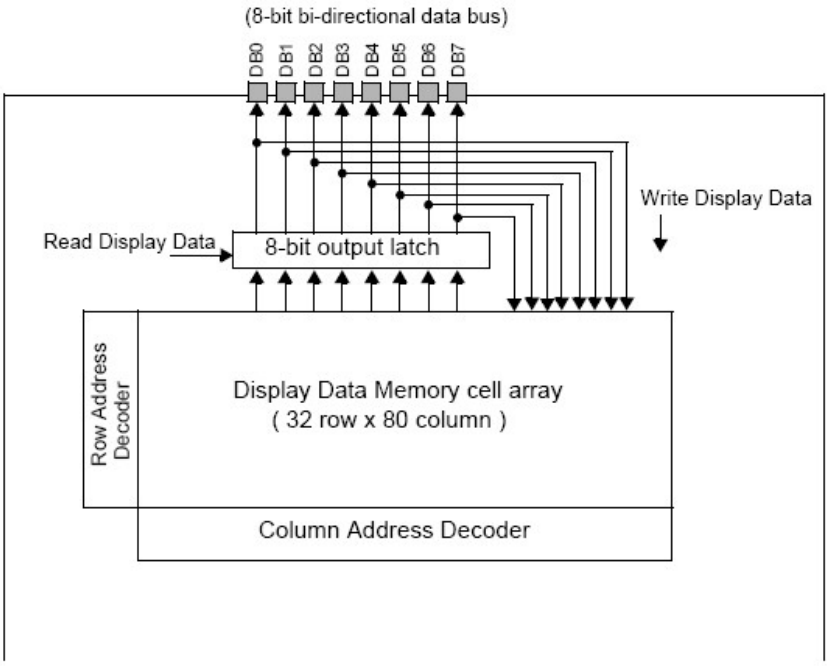


Fig.16 Read Display Data Memory

The setting of the control bus for issuing Read Display Data command

$\overline{C}$/D	E/($\overline{RD}$)	R/$\overline{W}$($\overline{WR}$)
1	0	1

Read-Modify-Write

When the Read-Modify-Write command is issued, the SBN1661G_X enters into Read-Modify-Write mode. In normal operation, when a Read Display Data command or a Write Display Data command is issued, the content of the Column Address Register is automatically incremented by one after the command operation is finished. However, during Read-Modify-Write mode, the content of the Column Address Register is not incremented by one after a Read Display Data command is finished; only the Write Display Data command can make the content of the Column Address Register automatically incremented by one after the command operation is finished.

During Read-Modify-Write mode, any other registers, except the Column Address Register, can be modified. This command is useful when a block of the Display Data Memory needs to be repeatedly read and updated.

Fig. 17 gives the change sequence of the Column Address Register during Read-Modify-Write mode. Figure 18 gives the flow chart for Read-Modify-Write command.

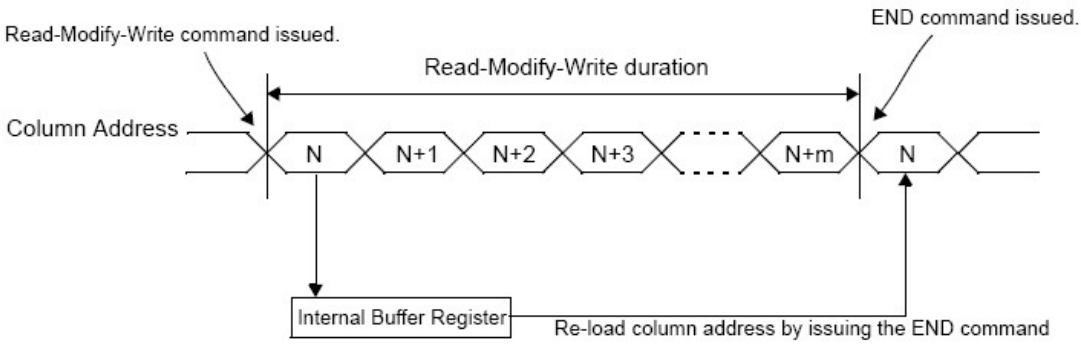


Fig.17 Column address change during Read-Modify-Write

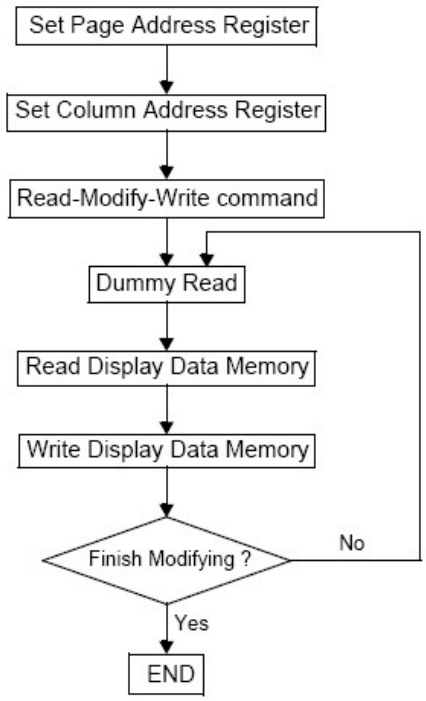


Fig.18 The flowchart for Read-Modify-Write

The setting of the control bus for the Read-Modify-Write command

$\overline{C}$/D	E/($\overline{RD}$)	R/$\overline{W}$($\overline{WR}$)
0	1	0

The setting of the data bus for the Read-Modify-Write command

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	0	0

The END command

The END command releases the Read-Modify-Write mode and re-loads the Column Address Register with the value previously stored in the internal buffer (refer to Fig. 17) when the Read-Modify-Write command was issued.

The setting of the control bus for the END command

$\overline{C}$/D	E/($\overline{RD}$)	R/$\overline{W}$($\overline{WR}$)
0	1	0

The setting of the data bus for the END command

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	1	1	1	0

The command code is EE Hex.

Software RESET command

The Software Reset command is different from the hardware reset and can not be used to replace hardware reset.

When Software Reset is issued by the host microcontroller,

• the content of the Display Start Line Register is cleared to zero(A4~A0=00000),
• the Page Address Register is set to 3 (A1 A0 = 11),
• the content of the Display Data Memory remains unchanged.
• the content of all other registers remains unchanged.

The setting of the control bus for Software RESET

$\overline{C}$/D	E/($\overline{RD}$)	R/$\overline{W}$($\overline{WR}$)
0	1	0

The setting of the data bus for Software RESET

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	1	0

The command code is E2 Hex.

Timing Characteristics

CL and FR timing

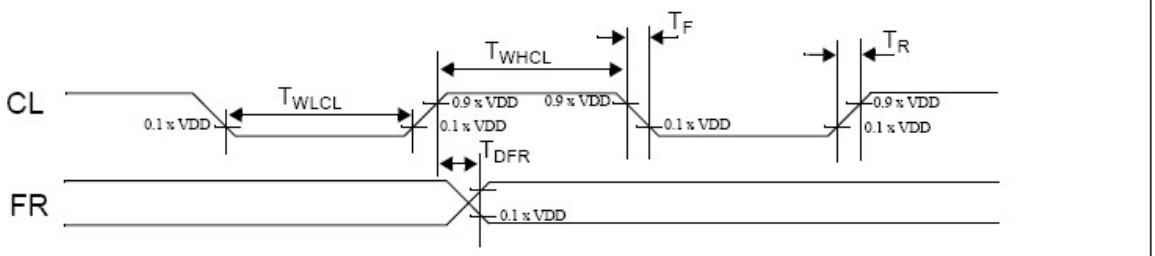


Fig.21 Display Control Signal Timing

CL and FR timing characteristics at VDD=5 volts
VDD = 5 V ±10%; VSS = 0 V; all voltages with respect to VSS unless otherwise specified;
Tamb = −20 to +75 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
T_{WHCL}	CL clock high pulse width		33			µs
T_{WLCL}	CL cock low pulse width		33			µs
T_R	CL clock rise time			28	120	ns
T_F	CL clock fall time			28	120	ns
$T_{DFR(input)}$	FR delay time (input)	When used as input in Slave Mode application	-2.0	0.2	1.6	µS
$T_{DFR(output)}$	FR delay time (output)	When used as output in Master Mode application, with CL= 100 pF.		0.2	0.36	µS

CL and FR timing characteristics at VDD=3 volts
VDD = 3 V ±10%; VSS = 0 V; all voltages with respect to VSS unless otherwise specified;
Tamb = −20 to +75 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
T_{WHCL}	CL clock high pulse width		65			µs
T_{WLCL}	CL cock low pulse width		65			µs
T_R	CL clock rise time			50	220	ns
T_F	CL clock fall time			50	220	ns
$T_{DFR(input)}$	FR delay time (input)	When used as input in Slave Mode application	-3.6	0.36	3.6	µS
$T_{DFR(output)}$	FR delay time (output)	When used as output in Master Mode application, with CL= 100 pF.		0.32	0.6	µS

AC timing for interface with an 80-type microcontroller

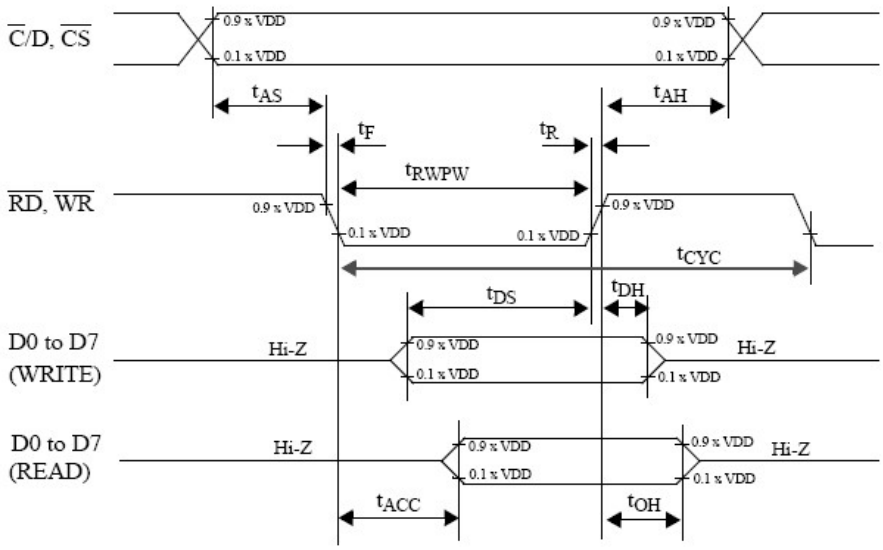


Fig.22 AC timing for interface with a 80-type microcontroller

AC timing for interface with a 80-type microcontroller at VDD=5 volts VDD = 5 V ±10%; VSS = 0 V; Tamb = -20 °C to +75°C.

symbol	parameter	min.	max.	test conditons	unit
t_{AS}	Address set-up time	20			ns
t_{AH}	Address hold time	10			ns
t_F, t_R	Read/Write pulse falling/rising time		15		ns
t_{RWPW}	Read/Write pulse width	200			ns
t_{CYC}	System cycle time	1000			ns
t_{DS}	Data setup time	80			ns
t_{DH}	Data hold time	10			ns
t_{ACC}	Data READ access time		90	CL= 100 pF.	ns
t_{OH}	Data READ output hold time	10	60	Refer to Fig. 23.	ns

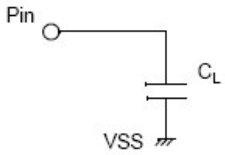
AC timing for interface with an 80-type microcontroller at VDD=3 volts VDD = 3 V ±10%; VSS = 0 V; Tamb = -20 °C to +75°C.

symbol	parameter	min.	max.	test conditons	unit
t_{AS}	Address set-up time	40			ns
t_{AH}	Address hold time	20			ns
t_F, t_R	Read/Write pulse falling/rising time		15		ns
t_{RWPW}	Read/Write pulse width	400			ns
t_{CYC}	System cycle time	2000			ns
t_{DS}	Data setup time	160			ns

symbol	parameter	min.	max.	test conditons	unit
t_{DH}	Data hold time	20			ns
t_{ACC}	Data READ access time		180	CL= 100 pF,	ns
t_{OH}	Data READ output hold time	20	120	Refer to 23.	ns

Note:

The measurement is with the load circuit connected. The load circuit is shown in Fig. 23.



C_L= 100 pF (including wiring and probe capacitance).

Fig.23 Load circuit.

AC timing for interface with a 68-type microcontroller

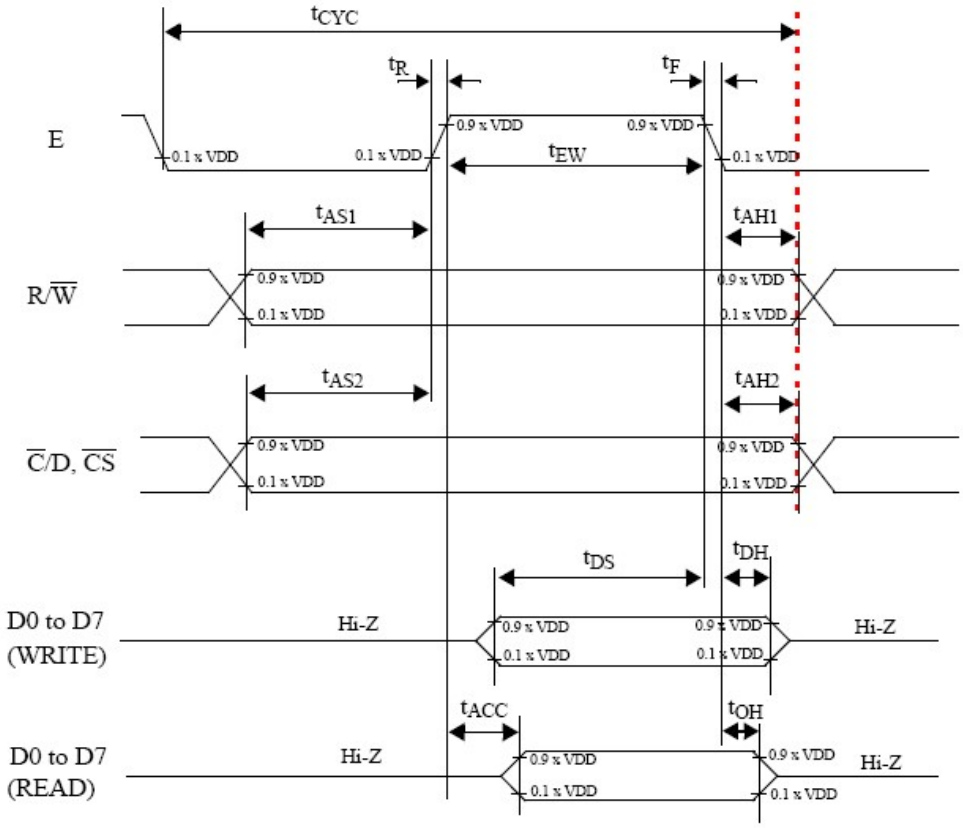


Fig.24 AC timing for interface with a 68-type microcontroller

AC timing for interface with a 68-type microcontroller at VDD=5 volts VDD = 5 V ±10%; VSS = 0 V; Tamb = -20 °C to +75°C.

symbol	parameter	min.	max.	test conditons	unit
t_{AS1}	Address set-up time with respect to R/$\overline{W}$	20			ns
t_{AS2}	Address set-up time with respect to $\overline{C}$/D, $\overline{CS}$	20			ns
t_{AH1}	Address hold time with respect to R/$\overline{W}$	10			ns
t_{AH2}	Address hold time respect with to $\overline{C}$/D, $\overline{CS}$	10			ns
t_F, t_R	Enable (E) pulse falling/rising time		15		ns
t_{CYC}	System cycle time	1000		Note 1	ns
t_{EWR}	Enable pulse width for READ	100			ns
t_{EWW}	Enable pulse width for WRITE	80			ns
t_{DS}	Data setup time	80			ns
t_{DH}	Data hold time	10			ns
t_{ACC}	Data access time		90	CL= 100 pF.	ns
t_{OH}	Data output hold time	10	60	Refer to Fig. 23.	ns

AC timing for interface with a 68-type microcontroller at VDD=3 volts VDD = 3 V ±10%; VSS = 0 V; Tamb = -20 °C to +75°C.

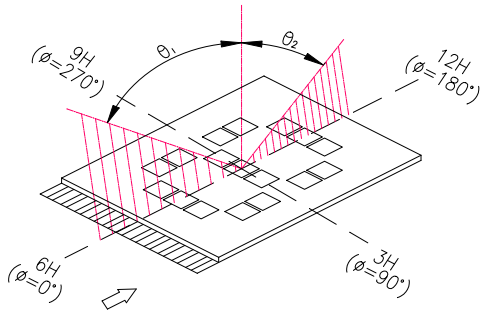
symbol	parameter	min.	max.	test conditons	unit
t_{AS1}	Address set-up time with respect to R/$\overline{W}$	40			ns
t_{AS2}	Address set-up time with respect to $\overline{C}$/D, $\overline{CS}$	40			ns
t_{AH1}	Address hold time with respect to R/$\overline{W}$	20			ns
t_{AH2}	Address hold time respect with to $\overline{C}$/D, $\overline{CS}$	20			ns
t_F, t_R	Enable (E) pulse falling/rising time		15		ns
t_{CYC}	System cycle time	2000		Note 1	ns
t_{EWR}	Enable pulse width for READ	200			ns
t_{EWW}	Enable pulse width for WRITE	160			ns
t_{DS}	Data setup time	160			ns
t_{DH}	Data hold time	20			ns
t_{ACC}	Data access time		180	CL= 100 pF.	ns
t_{OH}	Data output hold time	20	120	Refer to Fig. 23.	ns

Note:
1. The system cycle time(tCYC) is the time duration from the time when Chip Enable is enabled to the time when Chip Select is released.

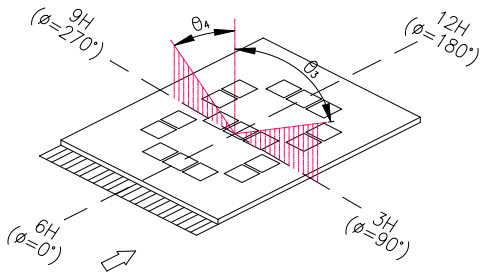
5 OPTICAL SPECIFICATION (STN Characteristics).

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	CR≧2	10	—	105	deg
	(H) φ	CR≧2	-30	—	30	deg
Contrast Ratio	CR	—	-	3	—	—
Response Time	T rise	—	—	200	300	ms
	T fall	—	—	200	300	ms

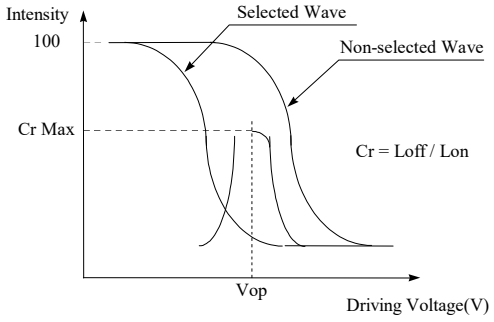
Note 1: definition of viewing angle θ1 & θ2



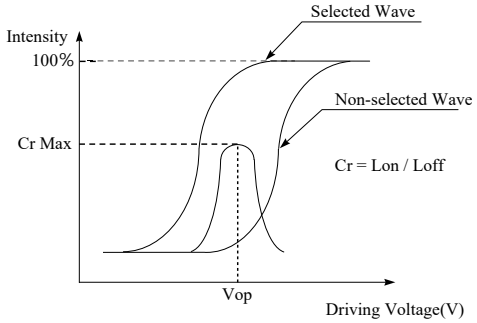
Note 2: definition of viewing angle θ3 & θ4



Note 3: definition of contrast ratio (CR)

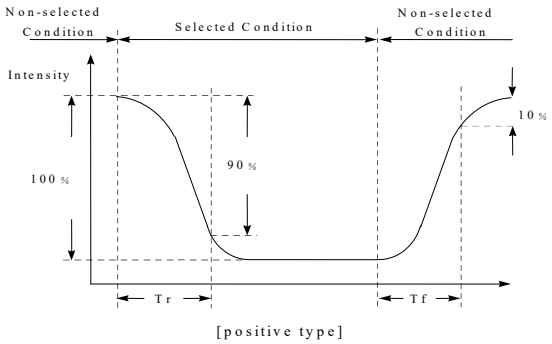


[positive type]

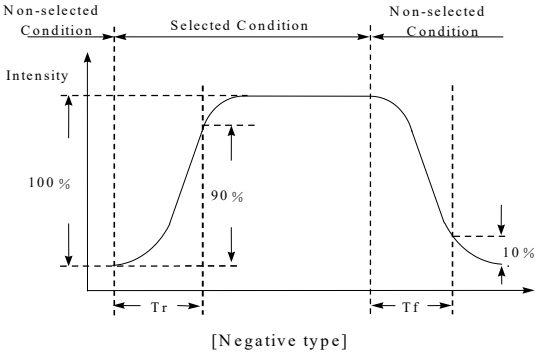


[Negative type]

Note 4: definition of response time



[positive type]



[Negative type]

6 TOUCH SCREEN SPECIFICATION

Under Development/evaluation

7 BACKLIGHT SPECIFICATION

7.1 LED BACKLIGHT CHARACTERISTICS

7.1.1 WHITE EDGE LED BACKLIGHT CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	32	40	60	mA	V=3.5V
Supply Voltage	V	—	3.5	3.6	V	—
Reverse Voltage	VR	—	—	5	V	—
Luminous Intensity	IV	10	—	—	CD/M^2	ILED=40mA
Wave Length	λp	—		—	nm	ILED=40mA
Life Time	—	—	10000	—	Hr.	V≦4.6V
Color	White					

7.1.2 YELLOW GREEN STANDARD LED BACKLIGHT CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	—	120	240	mA	V=4.2V
Supply Voltage	V	—	4.2	4.6	V	—
Reverse Voltage	VR	—	—	8	V	—
Luminous Intensity	IV	60	—	—	CD/M^2	ILED=120mA
Wave Length	λp	—	571	—	nm	ILED=120mA
Life Time	—	—	100000	—	Hr.	V≦4.6V
Color	Yellow Green					

7.1.3 BLUE LED BACKLIGHT CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	32	40	60	mA	V=3.2V
Supply Voltage	V	3.1	3.2	3.3	V	—
Reverse Voltage	VR	—	—	5	V	—
Luminous Intensity	IV	38.4	48	—	CD/M^2	ILED=40mA
Life Time (For Reference only)	—	—	30K	—	Hr.	ILED≦40Ma 25℃,50-60%RH, (Note 1)
Color	Blue					

7.1.4 GREEN LED BACKLIGHT CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	96	120	180	mA	V=4.2V
Supply Voltage	V	4.0	4.2	4.4	V	—
Reverse Voltage	VR	—	—	5	V	—
Luminous Intensity	IV	58	72	—	CD/M^2	ILED=120mA
Wave Length	λp	557	560	563	nm	ILED=120mA
Life Time	—	—	50K	—	Hr.	ILED≦120mA
Color	green					

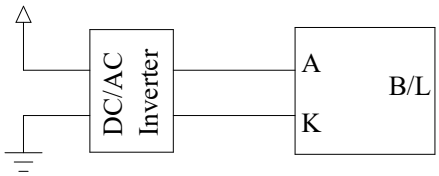
7.2 CCFL BACKLIGHT CHARACTERISTICS

NA

7.3 EL WHITE BACKLIGHT CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Drive Voltage	Vmax	—	110	—	Vrms	25℃
Drive Wave	Fmax	—	400	—	Hz	25℃
Brightness	—	29.6	37	—	cd/m^2	110V/400Hz
Power Consumption	—	—	27	—	mW	110V/400Hz
Chromatism	X	—	0.15	—	—	110V/400Hz
	Y	—	0.21	—	—	
Life time	—	2000hrs				110V/400Hz
Color	—	White				Light on 110V/400Hz

EL B\L drives directly from A , K.



8. QUALITY ASSURANCE SPECIFICATION

8.1CONFORMITY

The performance, function and reliability of the shipped products conform to the Product Specification.

8.2 DELIVERY ASSURANCE

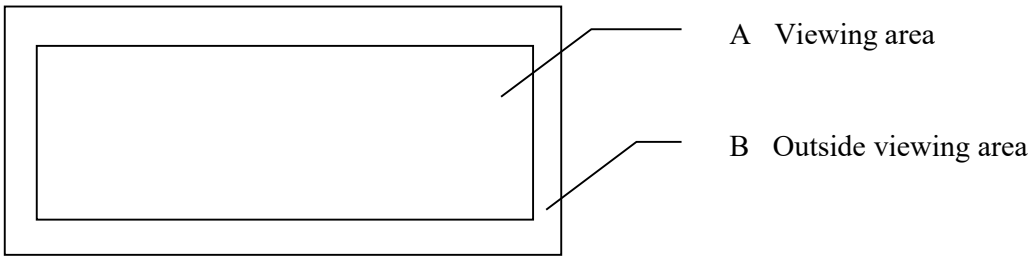
8.2.1 Delivery inspection standards.

- MIL-STD-105E, general inspection level II, single sampling level;
- IPC-AA610 rev. C, class 2 electronic assemblies standard

The quality assurance levels are shown below:

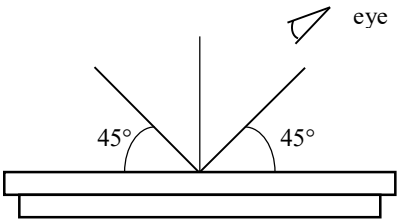
Rank	Item Inspected	Defect type	AQL	Remark
Critical defect	Display	Non display	0.65%	Display malfunction
		Over current		
		Missing segment		
		Wrong viewing direction		
		Backlight OFF		
	Dimension	PCB and bezel out of specification	0.65%	Assembly failure
Major defect	Display	Incorrect operating	1.0%	
	Backlight	Flashing, dust		
		Wrong colour		
Minor defect	LCD	Black and white spot	2.5%	Appearance defect
		Black and white lines		
		Polariser scratch		
		Bubbles in polariser		
		Segment deformation, pin hole		
		Colour uniformity		
		Glass chip		
	COB	Wire bond pad exposed		
		Insufficient covering with resin (wire bond line exposed)		
		Bubble, dust on COB		
	PCB	Dust, solder ball on PCB		
		Pad scratch		
		Total	2.5%	

8.2.2 Zone definition



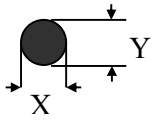
8.2.3 Visual inspection

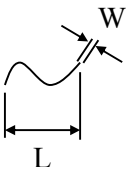
- Inspect under 2x20W or 40W fluorescent lamp (approximately 3000 lux) leaving 25 to 30 cm between the module and the lamp and 30 cm between the module and the eye (measuring position).
- Appearance is inspected at the best contrast voltage (best contrast is adjusted considering clearness and crosstalk on screen).
- Inspect the module at 45° right and left, top and bottom.
- Use the optimum viewing angle during the contrast inspection.

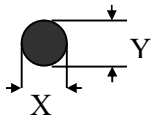


8.2.4 Standard of appearance inspection

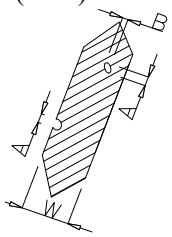
Units: mm

<table>
<tr><th>No</th><th>Item</th><th>Criteria</th></tr>
<tr><td>1</td><td>Black spot, white spot, dust</td><td>
Round type: as per following drawing
∅ = (X+Y)/2


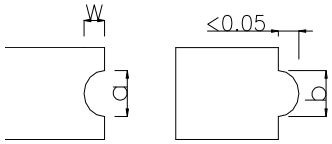
<table>
<tr><th colspan="3">Acceptable quantity</th></tr>
<tr><th>Size</th><th>Zone A</th><th>Zone B</th></tr>
<tr><td>∅<0.1</td><td>Any number</td><td rowspan="4">Any number</td></tr>
<tr><td>0.1<∅<0.2</td><td>6</td></tr>
<tr><td>0.2<∅<0.3</td><td>2</td></tr>
<tr><td>0.3<∅</td><td>0</td></tr>
</table>
Line type: as per following drawing


<table>
<tr><th colspan="4">Acceptable quantity</th></tr>
<tr><th>Length</th><th>Width</th><th>Zone A</th><th>Zone B</th></tr>
<tr><td>- -</td><td>W≤0.02</td><td>Any number</td><td rowspan="4">Any number</td></tr>
<tr><td>L≤3.0</td><td>0.02<W≤0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≤2.5</td><td>0.03<W≤0.05</td></tr>
<tr><td>- -</td><td>0.05<W</td><td>As round type</td></tr>
</table>
Total acceptable quantity: 3
</td></tr>
<tr><td>2</td><td>Polariser scratch</td><td>Scratch on protective film is permitted
Scratch on polariser: same as No. 1</td></tr>
<tr><td>3</td><td>Polariser bubble</td><td>
∅ = (X+Y)/2


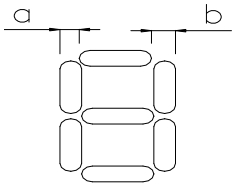
<table>
<tr><th colspan="3">Acceptable quantity</th></tr>
<tr><th>Size</th><th>Zone A</th><th>Zone B</th></tr>
<tr><td>∅<0.3</td><td>Any number</td><td rowspan="4">Any number</td></tr>
<tr><td>0.3<∅<1.0</td><td>3</td></tr>
<tr><td>1.0<∅<1.5</td><td>1</td></tr>
<tr><td>1.5<∅</td><td>0</td></tr>
</table>
Total acceptable quantity: 4
</td></tr>
<tr><td>4</td><td>Segment deformation</td><td>
1.a. Pin hole on segmented display

W: segment width
∅ = (A+B)/2


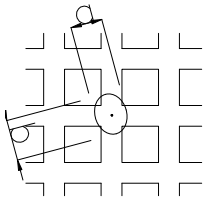
<table>
<tr><th colspan="2">Acceptable quantity</th></tr>
<tr><th>Width</th><th>∅</th></tr>
<tr><td>W≤0.4</td><td>∅≤0.2 and ∅≤1/2W</td></tr>
<tr><td>W>0.4</td><td>∅≤0.25 and ∅≤1/3W</td></tr>
</table>
Total acceptable quantity: 1 defect per segment
Pin holes with ∅ under 0.10 mm are acceptable
</td></tr>
</table>

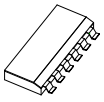
<table>
<tr><th>No</th><th>Item</th><th>Criteria</th></tr>
<tr><td>4</td><td>Segment deformation</td><td>
1b. Pin hole on dot matrix display


<table>
<tr><td colspan="2">Acceptable quantity</td></tr>
<tr><td>Size</td><td></td></tr>
<tr><td>a,b<0.1</td><td>Any number</td></tr>
<tr><td>(a+b)/2≤0.1</td><td>Any number</td></tr>
<tr><td>0.5<∅<1.0</td><td>3</td></tr>
</table>
Total acceptable quantity: 7

2. Segments / dots with different width


<table>
<tr><td colspan="2">Acceptable</td></tr>
<tr><td>a≥b</td><td>a/b≤4/3</td></tr>
<tr><td>a<b</td><td>a/b>4/3</td></tr>
</table>

3. Alignment layer defect
∅ = (a+b)/2


<table>
<tr><td colspan="2">Acceptable quantity</td></tr>
<tr><td>Size</td><td></td></tr>
<tr><td>∅≤0.4</td><td>Any number</td></tr>
<tr><td>0.4<∅≤1.0</td><td>5</td></tr>
<tr><td>1.0<∅≤1.5</td><td>3</td></tr>
<tr><td>1.5<∅≤2.0</td><td>2</td></tr>
</table>
Total acceptable quantity: 7
</td></tr>
<tr><td>5</td><td>Colour uniformity</td><td>Level of sample for approval set as limit sample</td></tr>
<tr><td>6</td><td>Backlight</td><td>The backlight colour should correspond to the product specification
Flashing and or unlit backlight is not allowed
Dust larger than 0.25 mm is not allowed</td></tr>
<tr><td>7</td><td>COB</td><td>Exposed wire bond pad is not allowed
Insufficient covering with resin is not allowed (wire bond line exposed)
Dust or bubble on the resin are not allowed</td></tr>
<tr><td>8</td><td>PCB
  </td><td>No unmelted solder paste should be present on PCB
Cold solder joints, missing solder connections, or oxidation are not allowed
No residue or solder balls on PCB are allowed
Short circuits on components are not allowed</td></tr>
</table>

9 RELIABILITY SPECIFICATION

Test Item	Test Condition	Description
High Temperature Operation	50°C or 70℃ 200hrs	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.
Low Temperature Operation	0°C or -20℃ 200hrs	Endurance test applying the electric stress under low temperature for a long time.
High Temperature Storage	70°C or 80℃ 200hrs	Endurance test applying the high storage temperature for a long time.
Low Temperature Storage	-20°C or -30℃ 200hrs	Endurance test applying the high storage temperature for a long time.
High Temperature & High Humidity Storage	80℃,90%RH 96hrs	Endurance test applying the high temperature and high humidity storage for a long time.
Thermal Shock Test	-30℃ 25℃ 80℃ 30min 5min 30min For 10 cycles	Endurance test applying the low and high temperature cycle. Burn In Test.
Vibration	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hrs	Endurance test applying the vibration during transportation and using.
ESD	VS=800V,RS=1.5kΩ CS=100pF	Endurance test applying the electric stress to the terminal.
Shock Test	50G Half sign wave 11 msedc 3 times of each direction	Constructional and mechanical endurance test applying the shock during transportation.

10 HANDLING PRECAUTIONS

Safety
If the LCD panel breaks, be careful not to get the liquid crystal fluid in your mouth or in your eyes.
If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water.

Mounting and Design
Place a transparent plate (e.g. acrylic, polycarbonate or glass) on the display surface to protect the display from external pressure. Leave a small gap between the transparent plate and the display surface.
When assembling with a zebra connector, clean the surface of the pads with alcohol and keep the surrounding air very clean.
Design the system so that no input signal is given unless the power supply voltage is applied.

Caution during LCD cleaning
Lightly wipe the display surface with a soft cloth soaked with Isopropyl alcohol, Ethyl alcohol or Trichlorotriflorothane.
Do not wipe the display surface with dry or hard materials that will damage the polariser surface.
Do not use aromatic solvents (toluene and xylene), or ketonic solvents (ketone and acetone).

Caution against static charge
As the display uses C-MOS LSI drivers, connect any unused input terminal to VDD or VSS. Do not input any signals before power is turned on.
Also, ground your body, work/assembly table and assembly equipment to protect against static electricity.

Packaging
Displays use LCD elements, and must be treated as such. Avoid strong shock and drop from a height.
To prevent displays from degradation, do not operate or store them exposed directly to sunshine or high temperature/humidity.

Caution during operation
It is indispensable to drive the display within the specified voltage limit since excessive voltage shortens its life.
Direct current causes an electrochemical reaction with remarkable deterioration of the display quality. Give careful consideration to prevent direct current during ON/OFF timing and during operation.
Response time is extremely delayed at temperatures lower than the operating temperature range while, at high temperatures, displays become dark. However, this phenomenon is reversible and does not mean a malfunction or a display that has been permanently damaged.
If the display area is pushed on hard during operation, some graphics will be abnormally displayed but returns to a normal condition after turning off the display once.
Even a small amount of condensation on the contact pads (terminals) can cause an electro-chemical reaction which causes missing rows and columns. Give careful attention to avoid condensation.

Storage
Store the display in a dark place where the temperature is 25°C ± 10°C and the humidity below 50%RH.
Store the display in a clean environment, free from dust, organic solvents and corrosive gases.
Do not crash, shake or jolt the display (including accessories).